




PCN Number:	20210222000.1		PCN Date:	Feb 22, 2021	
Title:	Qualification of Carsem Suzhou as an additional Assembly site for Select Devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	May 22, 2021	Estimated Sample Availability:	Date provided at sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification Carsem Suzhou as an additional assembly site for the list of devices below. Current assembly site and Material differences are as follows:					
		CDAT	Carsem		
	Mount Compound	4207123	444337		
	Mold Compound	4222198	444567		
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp		
Changes to product identification resulting from this PCN:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
TI Chengdu	CDA	CHN	Chengdu		
Carsem	CSZ	CHN	Jiangsu		
Sample product shipping label (not actual product label)					
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2d:		 Pb G4		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS	
MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750					

Product Affected:	
THS6222IRHFR	THS6222IRHFT

Qualification Report

Approve Date 18-Feb-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>THS6222IRHFR</u>	QBS Product Reference: <u>THS6222IRHFR</u>	QBS Process Reference: <u>OPA2810IDGK</u>	QBS Process Reference: <u>THS3491IDDA</u>	QBS Package Reference: <u>TPS53688RSB</u> <u>B0</u>
HTOL	High Temperature Operating Life Test, 70C ^A	300 Hours	-	-	-	3/231/0	-
HTOL	High Temperature Operating Life Test, 78C ^A	300 Hours	-	1/77/0	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0	-	1/77/0
EFR	Early Life Failure Rate, 70C ^A	24 Hours	-	-	-	3/3000/0	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/3000/0	-	-
HBM	ESD - HBM	2500 V	-	-	3/9/0	3/9/0	1/3/0
HBM	ESD - HBM	3000 V	-	-	-	-	-
HBM	ESD - HBM	3500 V	-	1/3/0	-	-	-
CDM	ESD - CDM	1000 V	-	-	-	3/9/0	1/3/0
CDM	ESD - CDM	1250 V	-	1/3/0	-	-	-
CDM	ESD - CDM	1500 V	-	-	3/9/0	-	-
LU	Latch-up	Per JESD78	-	1/6/0	3/18/0	3/30/0	1/6/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	3/90/0	3/90/0	-
AC	Autoclave 121C	96 Hours	-	-	-	-	1/77/0
HAST	Biased HAST, 130C/85%RH	96 Hours	2/154/0	3/231/0	3/231/0	3/231/0	1/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	1/77/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

^A Self heating of die brings Tj up to 150C

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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